



Material Content Data Sheet



Sales Product Name				SPD04N60S5		Issued		25. September 2017	
MA#				MA000851446					
Package				PG-TO252-3-311		Weight*		314.66 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.191	1.01	1.01	10141	10141	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137		
	non noble metal	iron	7439-89-6	0.143	0.05		455		
	non noble metal	copper	7440-50-8	143.098	45.47	45.53	454767	455359	
	non noble metal	aluminium	7429-90-5	0.522	0.17	0.17	1659	1659	
wire	inorganic material	antimonytrioxide	1309-64-4	1.984	0.63		6305		
encapsulation	plastics	brominated resin	-	2.125	0.68		6755		
	organic material	carbon black	1333-86-4	2.267	0.72		7205		
	plastics	epoxy resin	-	19.129	6.08		60794		
	inorganic material	silicondioxide	60676-86-0	116.193	36.93	45.04	369265	450324	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11886	11886	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	275	276	
solder	non noble metal	tin	7440-31-5	0.059	0.02		187		
	noble metal	silver	7440-22-4	0.073	0.02		233		
	non noble metal	lead	7439-92-1	2.804	0.89	0.93	8910	9330	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.09	6.10	60946	61025	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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